

Amendment/Response

Reply to Office Action of January 28, 2008

This listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of claims:

1. (currently amended) An apparatus, comprising:
 - a non-metallic substrate;
 - an electrically conducting film deposited on said substrate, wherein said film is a metal other than Cr, or said film is a metallic alloy other than Cr-alloy when said substrate is Ge or Si, or said film is a multilayered film which includes at least one metallic layer;
 - wherein said apparatus does not contain a p-n junction or a pin junction;
 - wherein a juncture of said film and said substrate forms a plane;
 - wherein a current flow within said film is substantially parallel to said plane; and
 - wherein said substrate consists essentially of a substrate material having metastable bonds on its surface immediately before deposition of said film, which forms a bond with said film; and
 - ~~wherein said deposition is in at least a high vacuum environment.~~
2. (previously amended) An apparatus according to claim 1, wherein said substrate material is selected from the group consisting of non-metallic elements, non-metallic alloys, and non-metallic compounds, semiconducting compounds, halides, and co-deposited mixtures of incompatible systems.
3. (original) An apparatus according to claim 2, wherein said film is a material selected from the group consisting of Mn, Ag, Fe, and Cu.
4. (original) An apparatus according to claim 2, wherein said film is a material selected from the group consisting of Mn, Ag, Fe, Al, Au, Ni, Pd, Pt, Co, and their alloys.
5. (original) An apparatus according to claim 2, further comprising an overlayer on said conducting film, wherein said overlayer is selected from the group consisting of Ge, Si, As, B, Bi, C, Ga, Se, Te, Fe, Al, W, Mo, Ta, Nb, V, Hf, Zr, Re, semiconducting compounds, halides, and co-deposited mixtures of incompatible systems.
6. (original) An apparatus according to claim 1, wherein said film is a material selected from the group consisting of Mn, Ag, Fe, and Cu.

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7. (original) An apparatus according to claim 1, wherein said film is a material selected from the group consisting of Mn, Ag, Fe, Al, Au, Ni, Pd, Pt, Co, and their alloys.

8. (previously amended) An apparatus according to claim 1, wherein said film is less than about 0.2 nm thick and has an electrical resistivity of less than 4×10^{-6} Ohm•m.

9. (original) An apparatus according to claim 6, in which said substrate is less than 5 nm thick.

10-13. (cancelled)

14-40. Cancelled